

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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XPower

PRELIMINARY SPEC



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Features

- PLCC-4 package.
- Single color.
- High luminance.
- High power, operating current @350mA.
- Suitable for all SMT assembly methods.
- Package : 500pcs / reel.
- Moisture sensitivity level : level 4.
- Patent pending.
- RoHS compliant.

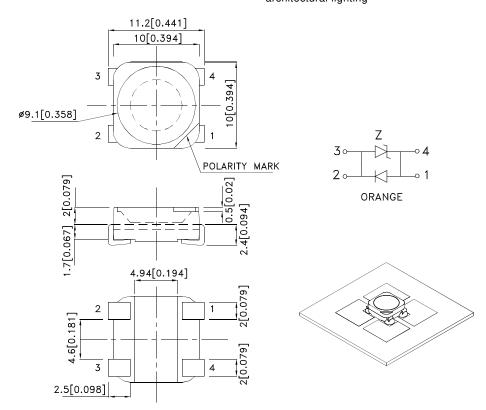
Part Number: AA1010SE28ZC Reddish-Orange



Applications

- •traffic signaling
- $\bullet \text{backlighting (illuminated advertising , general lighting)}$
- •interior and exterior automotive lighting
- •substitution of micro incandescent lamps
- •portable light source (e.g. bicycle flashlight)
- signal and symbol luminaire for orientation
- •marker lights (e.g. steps, exit ways, etc)
- •decorative and entertainment lighting
- •indoor and outdoor commercial and residential architectural lighting





Notes

- All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.
- 4. The device has a single mounting surface. The device must be mounted according to the specifications.





 SPEC NO: DSAH7221
 REV NO: V.3
 DATE: MAR/31/2009
 PAGE: 1 OF 5

 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: D.M.Su
 ERP:1201100042

Selection Guide

Part No.	Dice	Lens Type	luminous Intensity [2] lv(cd)@ 350mA		Фv (lm) [2] @ 350mA		Viewing Angle [1]
			Min.	Тур.	Min.	Тур.	201/2
AA1010SE28ZC	Reddish-Orange (AlGaInP)	WATER CLEAR	7.5	10	18	27	120°

Notes

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Value	Unit	
Power dissipation	Pt	1.05	W	
Junction temperature	TJ	110	°C	
Operating Temperature	Тор	-40 To +85	°C	
Storage Temperature	Tstg	-40 To +85	°C	
DC Forward Current [1]	lF	350	mA	
Peak Forward Current [2]	IFM	500	mA	
Thermal resistance [1]	Rth	60	°C/W	

Notes

Electrical / Optical Characteristics at TA=25°C

Parameter	Symbol	Value	Unit
Wavelength at peak emission IF=350mA [Typ.]	λpeak	640	nm
Dominant Wavelength IF=350mA [Typ.]	λDom [1]	625	nm
Spectral bandwidth at 50% PREL MAX IF=350mA [Typ.]	Δλ	30	nm
Forward Voltage IF=350mA [Min.]		2.0	
Forward Voltage IF=350mA [Typ.]	VF [2]	2.5	V
Forward Voltage IF=350mA [Max.]		3.0	
Temperature coefficient of λ peak IF=350mA, -10°C \leq T \leq 100°C [Typ.]	TCλpeak	0.14	nm/°C
Temperature coefficient of λdom I _{F=350mA} , -10°C≤ T≤100°C [Typ.]	TCλdom	0.12	nm/°C
Temperature coefficient of VF IF=350mA, -10°C≤ T≤100°C [Typ.]	TCv	-3.0	mV/°C

Notes:

1.Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

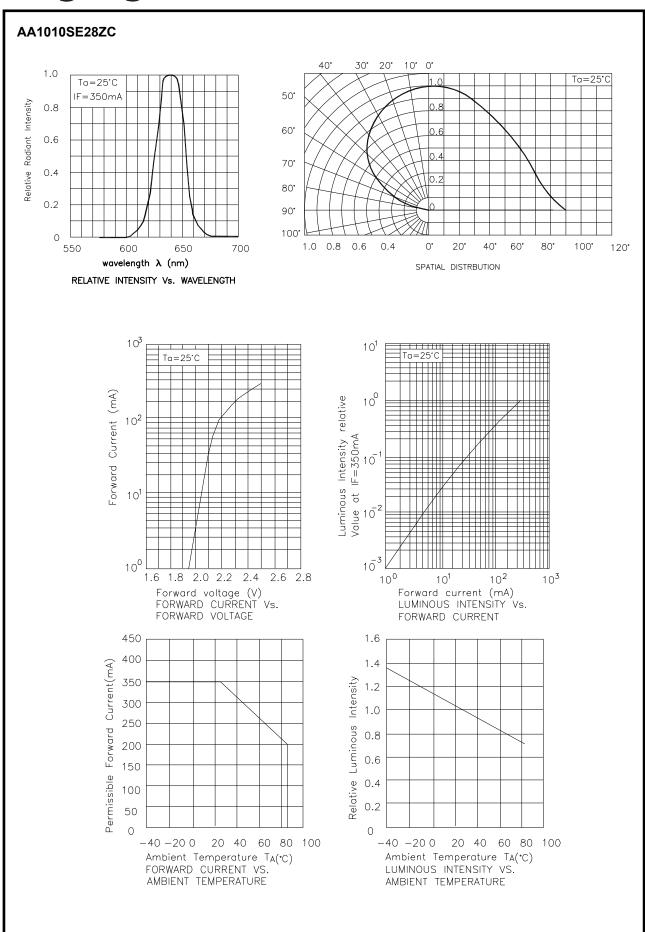
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APPROVED: WYNEC CHECKED: Allen Liu DRAWN: D.M.Su ERP:1201100042

 $^{1.\,\}theta1/2$ is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

^{2.} Luminous intensity / luminous Flux: +/-15%.

^{1.}Results from mounting on PC board FR4(pad size≥100mm² per pad), mounted on pc board-metal core PCB is recommend for lowest thermal Resistance.

 $^{2.1/10 \ \}mathsf{Duty} \ \mathsf{Cycle}, \ 0.1 \mathsf{ms} \ \mathsf{Pulse} \ \mathsf{Width}.$



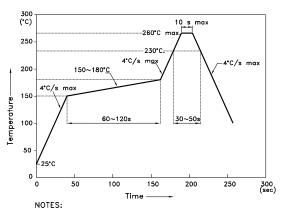
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AA1010SE28ZC

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



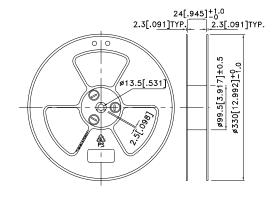
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

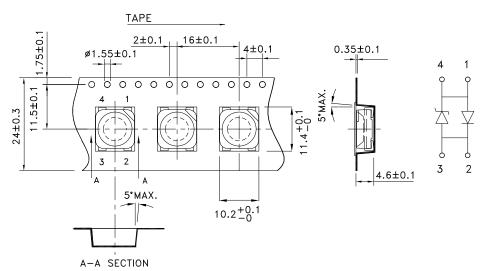
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ±0.1)

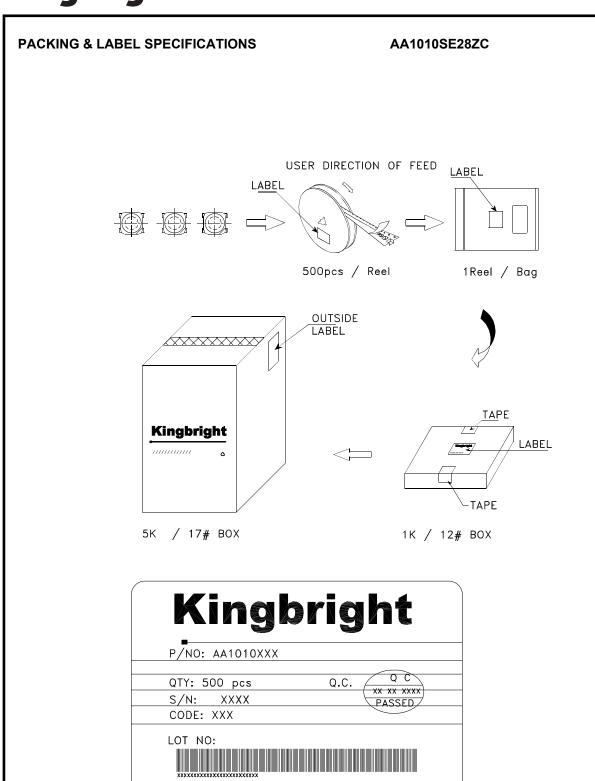
Reel Dimension



Tape Specifications (Units: mm)



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RoHS Compliant

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